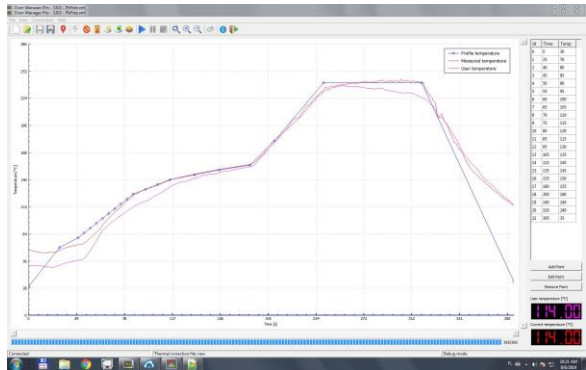


Reflow oven RK320



• Reflow oven RK 320

• Technical data

• Infrared + Air circulation + Air cooling, Pb-free Reflow Oven

- Surface mounting of units on boards require the exposure of the device package to high temperature to melt the lead finish for board soldering. A lot of the alternative "lead-free" solder materials being considered for use in IC assembly today require a peak soldering temperature of about 250 to 260 deg C, versus the peak temperature of 230 to 235 deg C for Sn-Pb solder. This means that lead-free IC's will need a higher temperature for board mounting, and will therefore be subjected to more severe thermo-mechanical stresses during the process.
- This Oven feature a complete system for today's solder/ Pb-Free solder(260C) requirement. The computer control system for free programable temperature curve. High power heating element with force air heating method provide a very even soldering hot zone across the total soldering area, This cost effective unit offer high production count (4~5 mins per cycle of 300mm x 220mm board) which ideal for low to medium size of SMD production. The static soldering process offer very stable non moving especially important for fine pitch SMD soldering.

Features:

- Infrared Array + Force Air (high volume, low pressure) heating method.
- Heating system for top and bottom - separately and selectively controlled
- Free programmable control for temperature curve setting.
- Dual channel air circulation - internal cooling fans for fast cool down performance
- Fully Automatic, fully static (non moving rail) operation, single or double side board soldering.
- Large transparent glass window see through the soldering process with high temperature
- Internal complete high gloss stainless steel construction, high IR efficiency and easy to clean, maintenance.
- Top Open design for quick access to heating element and service.
- Software for graphical interface mode – LAN and USB Interface for external PC

Specifications:

- Maximum heating area: 320mm x 220mm
- Heating system: top und bottom - separately and selectively controlled
- Free programable in graphical mode
- 4 thermocouples inside heating chamber
- 1 interface for additional thermocouple – direct measurement on the PCB
- Fume extractor interface – diameter 80mm
- Maximum Temperature: 290 °C
- Operation environment: 0-40 °C
- Maximum power consumption: 3500 W / 1200W typ.
- Weight: 38 kg gross, 57 kg ship
- Dimension: 555 mm x 480 mm x 300 mm
- Input Voltage: AC 230V / max. 16 A / 50-60 Hz